503077372 11/26/2014

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HUALONG SONG	10/24/2014

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION
Street Address:	18 ZHANGJIANG ROAD, PUDONG NEW AREA
City:	SHANGHAI
State/Country:	CHINA
Postal Code:	201203

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14554168

CORRESPONDENCE DATA

Fax Number:

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ATTORNEY DOCKET NUMBER:	00158.0174.00US
NAME OF SUBMITTER: MENG LIU	
SIGNATURE:	/Meng Liu/
DATE SIGNED:	11/26/2014
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 2

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PATENT 503077372 REEL: 034267 FRAME: 0650

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ASSIGNMENT AND DECLARATION

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

SEMICONDUCTOR DEVICES AND FABRICATION METHOD THEREOF
for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on(Application No); and
WHEREAS, Semiconductor Manufacturing International (Shanghai) Corporation, a corporation of P. R. China whose post office address is 18 Zhangiang Road, Pudong New Area, Shanghai, China 201203 (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;
NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, provisional Application No
AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;
AND, IWE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.
AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No, filed) the filing date and application number of said application when known.

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Further, as a below named inventor, I hereby declare that:	
This declaration is directed to the application attached hereto or United States applicat international application number filed on If the application is not attached hereto, the application is as identified above or by the attorney	ion or PCT
if the application is not attached hereto, the application is as identified above or by the attorney number as set forth above and/or the following.	docket
The above-identified application was made or authorized to be made by me.	
I believe that I am the original inventor or an original joint inventor of a claimed inventic application.	n in the
I have reviewed and understand the contents of the above-identified application, including claims.	ing the
I acknowledge the duty to disclose information which is material to patentability as defi- 37.Code of Federal Regulations § 1.56, including for continuation-in-part applications, material information which became available between the filing data of the prior application and the nati PCT International filing date of the continuation-in-part application.	
I hereby acknowledge that any willful false statement made in this declaration is punish 18 U.S.C. §1001 by fine or imprisonment of not more than five (5) years, or both.	iable under
IN TESTIMONY WHEREOF, I/We have hereunto set our hands.	
Inventor HUALONG SONG Legal Name:	
Signature: Hualong Sovig Date: 2014, 10, 2	4
	,
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, m accompany this form or must have been previously filed. Check the box below and complete the attacher list additional inventors.	ust f page(s) to

-2-

Additional inventors are being named on the __supplemental sheet(s) attached hereto.